# 1.8V to 3.3V LVCMOS High Performance Clock Buffer Family

# 5PB11xx

#### DATASHEET

#### Description

The 5PB11xx is a high-performance LVCMOS Clock Buffer Family. It has best-in-class Additive Phase Jitter of 50fsec RMS.

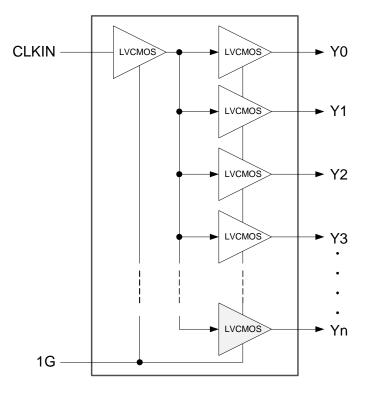
There are five different fan-out variations, 1:2 to 1:10, available.

The IDT5PB11xx also supports an Output Enable function. It comes in various packages and can operate from a 1.8V to 3.3V supply.

#### Features

- High performance 1:2, 1:4, 1:6, 1:8, 1:10 LVCMOS clock buffer
- Very low pin-to-pin skew <50ps
- Very low additive jitter <50fs
- Supply voltage: 1.8V to 3.3V
- fMAX = 200MHz
- Integrated serial termination for 50ohm channel
- Packaged in 8-, 14-, 16-, 20-pin TSSOP and small DFN and QFN packages
- Extended (-40°C to +105°C) temperature range

#### **Block Diagram**



## Pin Assignments for TSSOP Packages

CLKIN	1	5PB1102PGGI	8	Y1
1G	2		7	NC
Y0	3		6	VDD
GND	4		5	NC
CLKIN	1	5PB1104PGGI	8	Y1
1G	2		7	Y3
Y0	3		6	VDD
GND	4		5	Y2

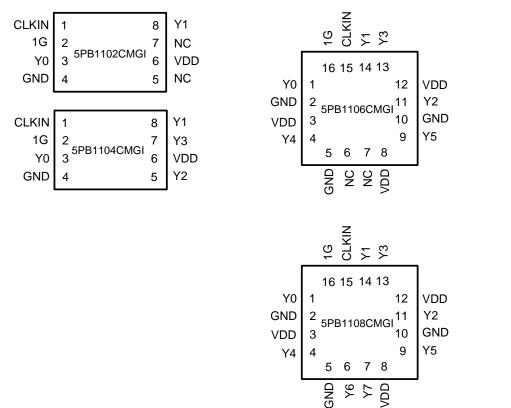
CLKIN	1		14	Y1
1G	2		13	Y3
Y0	3		12	VDD
GND	4	5PB1106PGGI	11	Y2
VDD	5		10	GND
Y4	6		9	Y5
GND	7		8	VDD
CLKIN	1		16	Y1
CLKIN 1G	1 2		16 15	Y1 Y3
	•			
1G	2	5PB1108PGGI	15	Y3
1G Y0	2 3	5PB1108PGGI	15 14	Y3 VDD
1G Y0 GND	2 3 4	5PB1108PGGI	15 14 13	Y3 VDD Y2
1G Y0 GND VDD	2 3 4 5	5PB1108PGGI	15 14 13 12	Y3 VDD Y2 GND

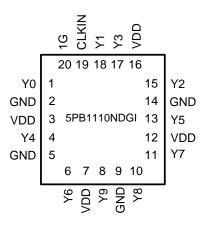
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CLKIN	1		20	Y1
1G	2		19	Y3
Y0	3		18	VDD
GND	4		17	Y2
VDD	5	5PB1110PGGI	16	GND
Y4	6		15	Y5
GND	7		14	VDD
Y6	8		13	Y7
VDD	9		12	Y8
Y9	10		11	GND

## Pin Descriptions for TSSOP Packages

Device Number	LVCMOS Clock Input	Clock Output Enable	LVCMOS Clock Output	Clock Output Supply Voltage	
	CLKIN	1G	Y0, Y1, Y9	Vdd	GND
5PB1102PGGI	1	2	3, 8	6	4
5PB1104PGGI	1	2	3, 8, 5, 7	6	4
5PB1106PGGI	1	2	3, 14, 11, 13, 6, 9	5, 8, 12	4, 7, 10
5PB1108PGGI	1	2	3, 16, 13, 15, 6, 11, 8, 9	5, 10, 14	4, 7, 12
5PB1110PGGI	1	2	3, 20, 17, 19, 6, 15, 8, 13, 12, 10	5, 9, 14, 18	4, 7, 11, 16

#### Pin Assignments for DFN/QFN Packages





#### Pin Descriptions for DFN/QFN Packages

Device Number	LVCMOS Clock Input	Clock Output Enable	LVCMOS Clock Output	Supply Voltage	Ground
	CLKIN	1G	Y0, Y1, Y9	Vdd	GND
5PB1102CMGI	1	2	3, 8	6	4
5PB1104CMGI	1	2	3, 5, 7, 8	6	4
5PB1106CMGI	15	16	1, 4, 9, 11, 13, 14	3, 8, 12	2, 5, 10
5PB1108CMGI	15	16	1, 4, 6, 7, 9, 11, 13, 14	3, 8, 12	2, 5, 10
5PB1110NDGI	19	20	1, 4, 6, 8, 10, 11, 13, 15, 17, 18	3, 7, 12, 16	2, 5, 9, 14

#### **Output Logic Table**

Ing	outs	Output
CLKIN	1G	Yn
Х	L	L
L	Н	L
Н	Н	Н

After at least three cycles of input clock toggling. Output Enable function is asynchronous.

#### **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the 5PB11xx. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	3.465V
Output Enable and All Outputs	-0.5 V to VDD+0.5 V
CLKIN	3.465V
Ambient Operating Temperature (extended)	-40 to +105°C
Storage Temperature	-65 to +150°C
Junction Temperature	125°C
Soldering Temperature	260°C

#### **Recommended Operation Conditions**

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature (extended)	-40		+105	°C
Power Supply Voltage (measured in respect to GND)	+1.71		+3.465	V

#### **DC Electrical Characteristics**

(VDD = 1.8V, 2.5V, 3.3V)

VDD=1.8V ±5%	, Ambient temperature -40° to +105°C, unless stated otherwise
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Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		1.71		1.89	V
Input High Voltage, CLKIN	V <sub>IH</sub>	Note 1	0.7xVDD		VDD	V
Input Low Voltage, CLKIN	V <sub>IL</sub>	Note 1			0.3xVDD	V
Input High Voltage, 1G	V <sub>IH</sub>		1.6		VDD	V
Input Low Voltage, 1G	V <sub>IL</sub>				0.6	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -5 mA	1.4			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 5 mA			0.4	V
Nominal Output Impedance	Z <sub>O</sub>			50		Ω
Input Capacitance	C <sub>IN</sub>	CLKIN, 1G pin		5		pF
Operating Supply Current	I			ŀ	1	<b>I</b>
5PB1102		100MHz, No load, 25°C		8		
5PB1104		100MHz, No load, 25°C		12		_
5PB1105	IDD	100MHz, No load, 25°C		16		mA
5PB1102		100MHz, No load, 25°C		21		
5PB1110		100MHz, No load, 25°C		25		

Notes: 1. Nominal switching threshold is VDD/2

#### VDD=2.5 V ±5%, Ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		2.375		2.625	V
Input High Voltage, CLKIN	V <sub>IH</sub>	Note 1	0.7xVDD		VDD	V
Input Low Voltage, CLKIN	V <sub>IL</sub>	Note 1			0.3xVDD	V
Input High Voltage, 1G	V <sub>IH</sub>		1.8		VDD	V
Input Low Voltage, 1G	V <sub>IL</sub>				0.7	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -8 mA	1.9			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 8 mA			0.5	V
Nominal Output Impedance	Z <sub>O</sub>			50		Ω
Input Capacitance	C <sub>IN</sub>	CLKIN, 1G pin		5		pF
Operating Supply Current						
5PB1102		100MHz, No load, 25°C		10		
5PB1104		100MHz, No load, 25°C		15		
5PB1105	IDD	100MHz, No load, 25°C		22		mA
5PB1102		100MHz, No load, 25°C		28		
5PB1110		100MHz, No load, 25°C		33		

#### VDD=3.3 V ±5% , Ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.15		3.45	V
Input High Voltage, CLKIN	V <sub>IH</sub>	Note 1	0.7xVDD		VDD	V
Input Low Voltage, CLKIN	V <sub>IL</sub>	Note 1			0.3xVDD	V
Input High Voltage, 1G	V <sub>IH</sub>		2		VDD	V
Input Low Voltage, 1G	V <sub>IL</sub>				0.8	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -12 mA	2.4			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 12 mA			0.7	V
Nominal Output Impedance	Z <sub>O</sub>			50		Ω
Input Capacitance	C <sub>IN</sub>	CLKIN, 1G pin		5		pF
Operating Supply Current	I		.1	1		L
5PB1102		100MHz, No load, 25°C		12		
5PB1104		100MHz, No load, 25°C		20		
5PB1105	IDD	100MHz, No load, 25°C		25		mA
5PB1102		100MHz, No load, 25°C		35		
5PB1110		100MHz, No load, 25°C		40		

# AC Electrical Characteristics (VDD = 1.8V, 2.5V, 3.3V)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t <sub>OR</sub>	0.36 to 1.44 V, C <sub>L</sub> =5 pF		0.8	1.0	ns
Output Fall Time	t <sub>OF</sub>	1.44 to 0.36 V, C <sub>L</sub> =5 pF		0.8	1.0	ns
Start-up Time	t <sub>START-UP</sub>	Part start-up time for valid outputs after VDD ramp-up			3	ms
Propagation Delay		Note 1		1.9	2.2	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew (5PB1102/04/06)		Rising edges at VDD/2, Note 2		35	50	ps
Output to Output Skew (5PB1108/10)		Rising edges at VDD/2, Note 2		45	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps
Output Enable Time	t <sub>EN</sub>	$C_{L} \leq 5 \text{ pF}$			3	cycles
Output Disable Time	t <sub>DIS</sub>	$C_{L} \leq 5 \text{ pF}$			3	cycles

$VDD = 2.5 V \pm 5\%$	, Ambient Temperature -40° to +105°C, unless stated otherwise
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Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t <sub>OR</sub>	0.5 to 2.0 V, C <sub>L</sub> =5 pF		0.75	1.0	ns
Output Fall Time	t <sub>OF</sub>	2.0 to 0.5 V, C <sub>L</sub> =5 pF		0.75	1.0	ns
Start-up Time	t <sub>START-UP</sub>	Part start-up time for valid outputs after VDD ramp-up			3	ms
Propagation Delay		Note 1		2.4	2.9	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew (5PB1102/04/06)		Rising edges at VDD/2, Note 2		35	50	ps
Output to Output Skew (5PB1108/10)		Rising edges at VDD/2, Note 2		45	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps
Output Enable Time	t <sub>EN</sub>	$C_{L} \leq 5  pF$			3	cycles
Output Disable Time	t <sub>DIS</sub>	$C_{L} \leq 5  pF$			3	cycles

VDD = 3.3 V ±5%, Ambien	t Temperature -40° to +105°C, unless stated otherwise
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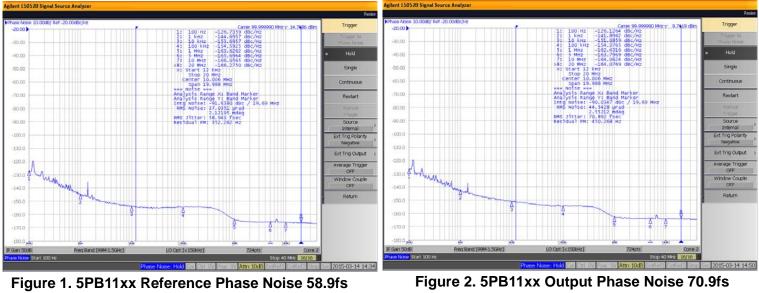
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t <sub>OR</sub>	0.66 to 2.64 V, C <sub>L</sub> =5 pF		0.7	1.0	ns
Output Fall Time	t <sub>OF</sub>	2.64 to 0.66 V, C <sub>L</sub> =5 pF		0.7	1.0	ns
Start-up Time	t <sub>START-UP</sub>	Part start-up time for valid outputs after VDD ramp-up			3	ms
Propagation Delay		Note 1		2	2.4	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew (5PB1102/04/06)		Rising edges at VDD/2, Note 2		35	50	ps
Output to Output Skew (5PB1108/10)		Rising edges at VDD/2, Note 2		45	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps
Output Enable Time	t <sub>EN</sub>	$C_{L} \leq 5  pF$			3	cycles
Output Disable Time	t <sub>DIS</sub>	$C_{L} \leq 5 \text{ pF}$			3	cycles

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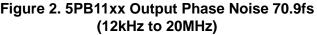
Notes: 1. With rail to rail input clock 2. Between any 2 outputs with equal loading. 3. Duty cycle on outputs will match incoming clock duty cycle. Consult IDT for tight duty cycle clock generators.

**IDT** 

#### **Phase Noise Plots**

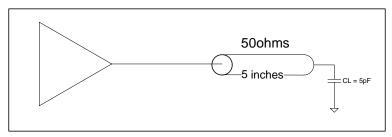


(12kHz to 20MHz)

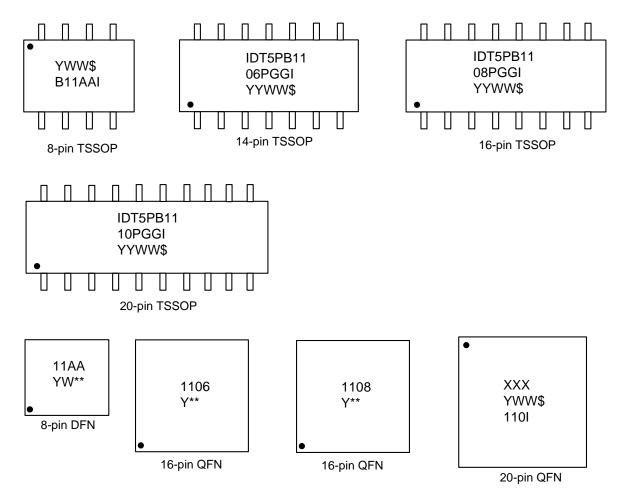


The phase noise plots above show the low Additive Jitter of the 5PB11xx high-performance buffer. With an integration range of 12kHz to 20MHz, the reference input has about 58.9fs of RMS phase jitter while the output of 5PB11xx has about 70.9fs of RMS phase jitter. This results in a low Additive Phase Jitter of only 39fs.

#### **Test Load and Circuit**



#### **Marking Diagrams**



Notes:

1. "AA" denotes the last two digits of the part number for 8-pin TSSOP and DFN (e.g. 02, 04).

2. "\*\*" is the lot sequence.

3. "XXX" denotes the last three characters of the Asm lot (20-pin QFN only).

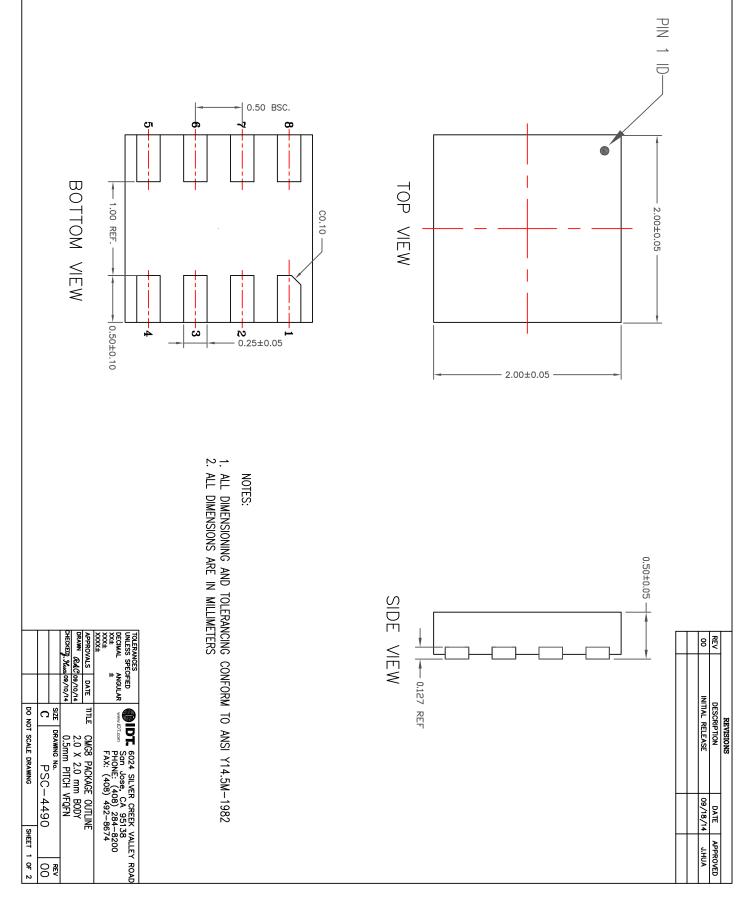
4. "YYWW", "YWW", "YW", or "Y" is the last digit(s) of the year and week that the part was assembled.

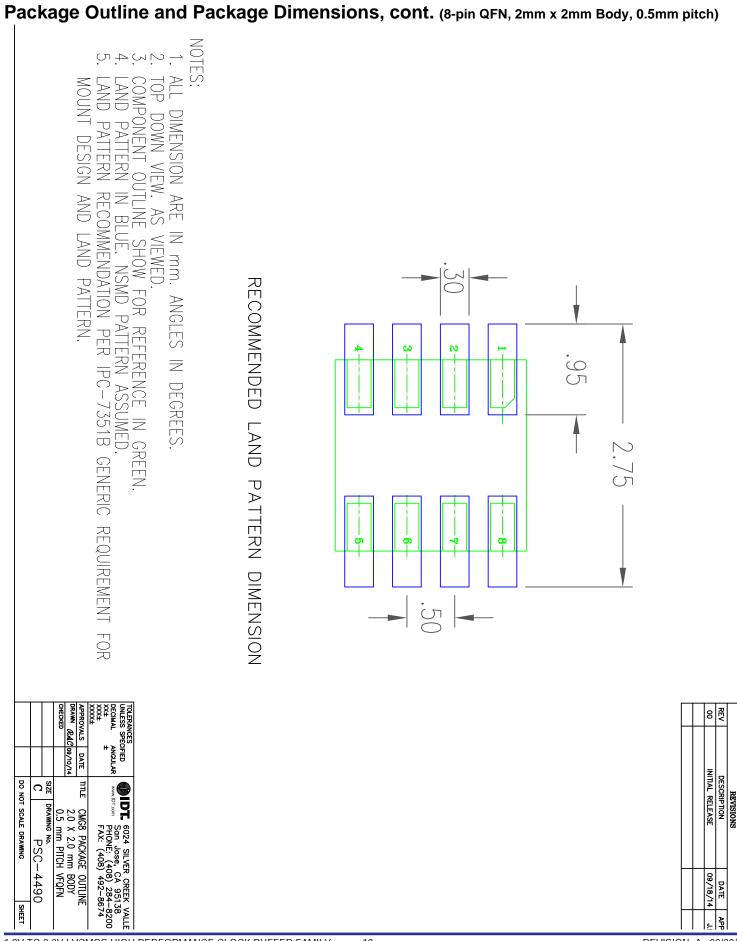
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- 5. "\$" denotes the mark code.
- 6. "G" after the two-letter package code denotes RoHS compliant package.
- 7. "I" denotes extended temperature range device.
- 8. Bottom marking: country of origin (TSSOP only).

## () IDT



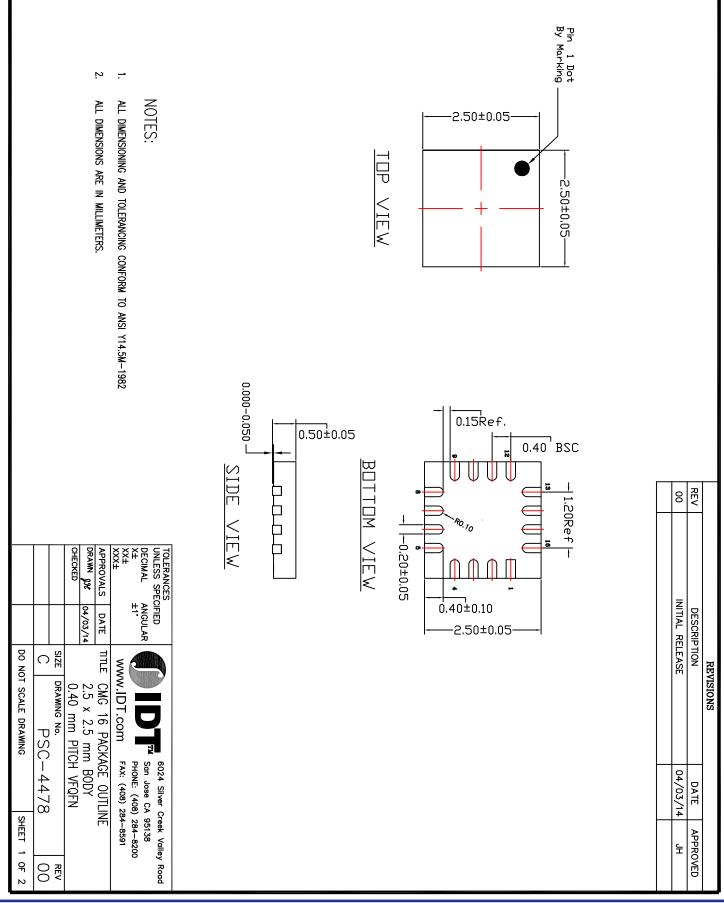




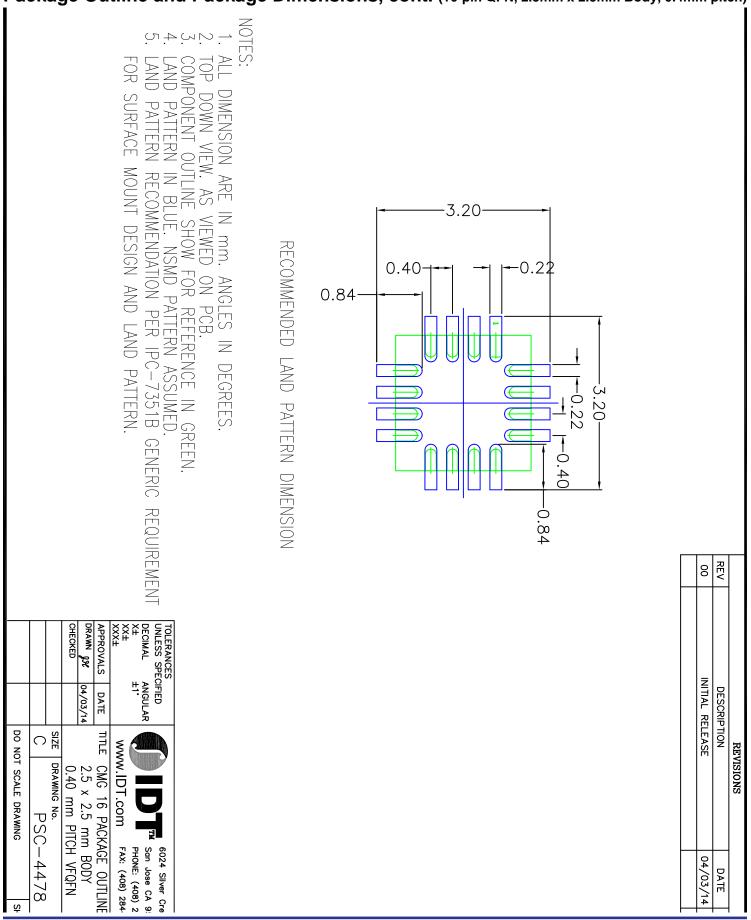




#### Package Outline and Package Dimensions (16-pin QFN, 2.5mm x 2.5mm Body, 0.4mm pitch)



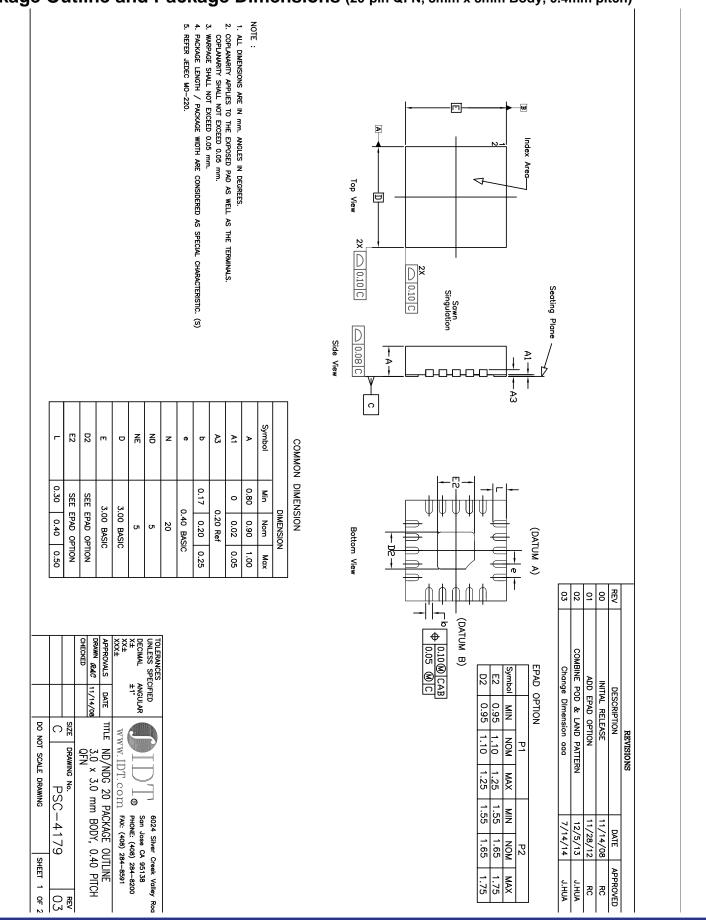
#### Package Outline and Package Dimensions, cont. (16-pin QFN, 2.5mm x 2.5mm Body, 0.4mm pitch)



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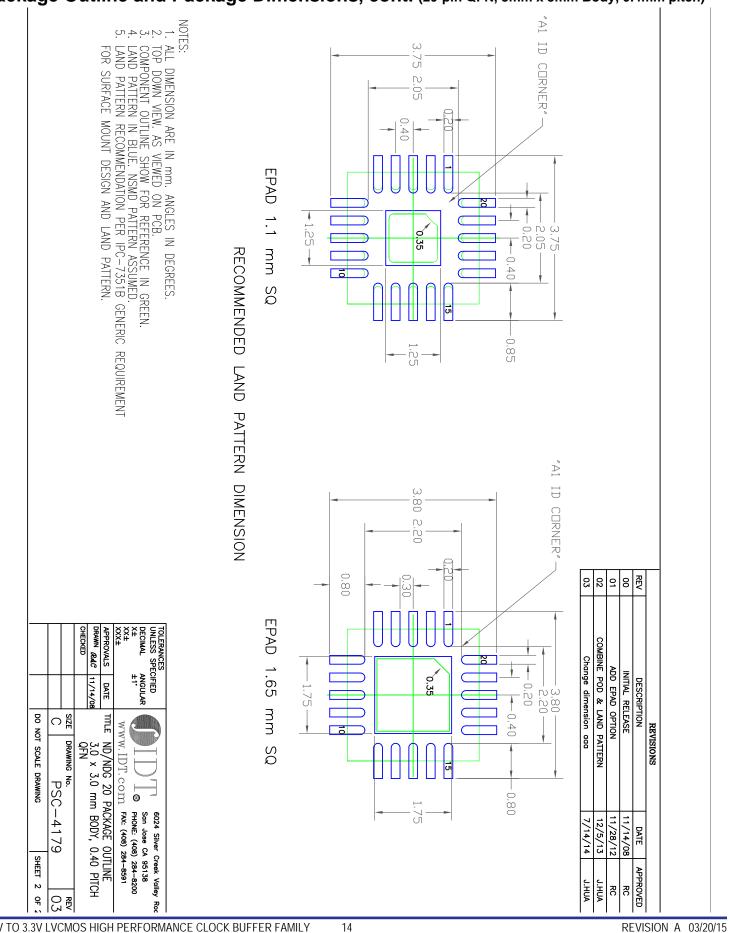
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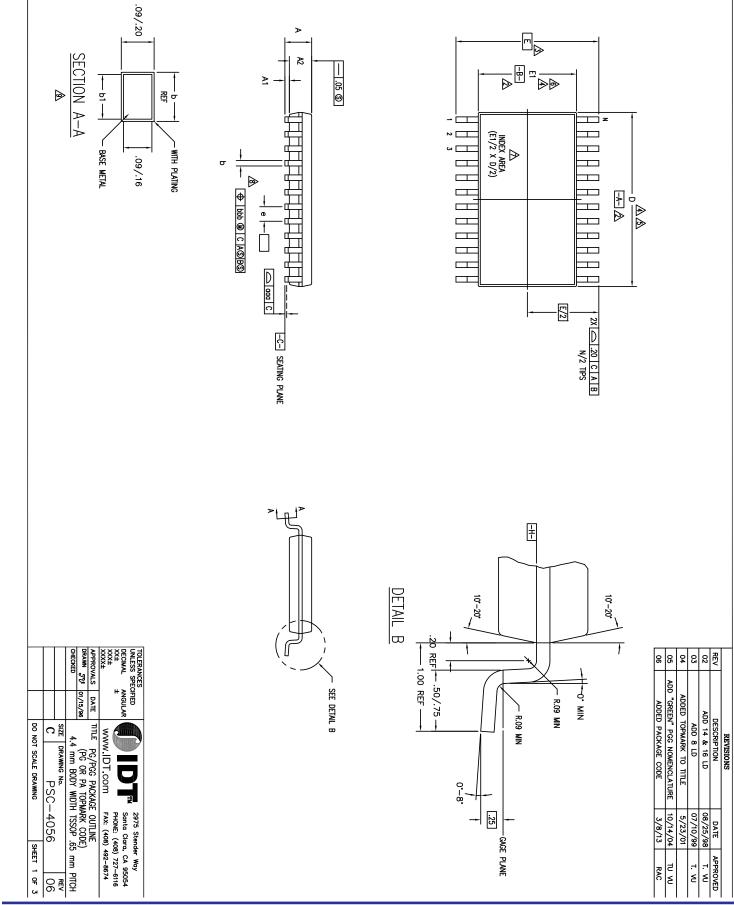
#### Package Outline and Package Dimensions, cont. (20-pin QFN, 3mm x 3mm Body, 0.4mm pitch)



1.8V TO 3.3V LVCMOS HIGH PERFORMANCE CLOCK BUFFER FAMILY



#### Package Outline and Package Dimensions (8-, 14-, 16-, 20-pin TSSOP)



## Package Outline and Package Dimensions, cont. (8-, 14-, 16-, 20-pin TSSOP)

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THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION AA, AB-1, AB, AC, AD & AE	ALL DIMENSIONS ARE IN MILLIMETERS	THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP	LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT	detail of Pin 1 identifier is optional but must be located within the zone indicated	dimension e1 does not include interlead flash or protrusions. Interlead Flash or protrusions shall not exceed .25 mm per side	DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE	DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE	DIMENSION E TO BE DETERMINED AT SEATING PLANE	Datums —A— and	ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994	NOTES:		1	1	.19 19	].	4.30			_	3	_	MN	JEDEC	
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VARIATION AA PG/PGG8

C VARIATION AB-1 PG/PGG14

VARIATION AB PG/PGG16

AC PG/PGG20

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ADDED TOPMARK TO TITLE ADD "GREEN" PGG NOMENCLATURE ADDED PACKAGE CODE

10/14/04 5/23/01 3/8/13

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RAC

DESCRIPTION ADD 14 & 16 LD ADD 8 LD REVISIONS

DATE 08/25/98 07/10/99

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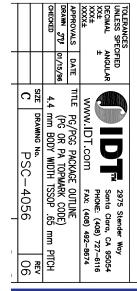
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## Package Outline and Package Dimensions, cont. (8-, 14-, 16-, 20-pin TSSOP)

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ADDED PACKAGE CODE	ADD "GREEN" PGG NOMENCLATURE	ADDED TOPMARK TO TITLE	ADD 8 LD	AUU 14 & 16 LU
3/8/13	10/14/04	5/23/01	07/10/99	R6/52/80
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#### REVISION A 03/20/15

## **Ordering Information**

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
5PB1102PGGI	see page 8	Tubes	8-pin TSSOP	-40 to +105 °C
5PB1102PGGI8		Tape and Reel	8-pin TSSOP	-40 to +105 °C
5PB1104PGGI		Tubes	8-pin TSSOP	-40 to +105 °C
5PB1104PGGI8		Tape and Reel	8-pin TSSOP	-40 to +105 °C
5PB1106PGGI		Tubes	14-pin TSSOP	-40 to +105 °C
5PB1106PGGI8		Tape and Reel	14-pin TSSOP	-40 to +105 °C
5PB1108PGGI		Tubes	16-pin TSSOP	-40 to +105 °C
5PB1108PGGI8		Tape and Reel	16-pin TSSOP	-40 to +105 °C
5PB1110PGGI		Tubes	20-pin TSSOP	-40 to +105 °C
5PB1110PGGI8		Tape and Reel	20-pin TSSOP	-40 to +105 °C
5PB1102CMGI		Cut Tape	8-pin DFN	-40 to +105 °C
5PB1102CMGI8		Tape and Reel	8-pin DFN	-40 to +105 °C
5PB1104CMGI		Cut Tape	8-pin DFN	-40 to +105 °C
5PB1104CMGI8		Tape and Reel	8-pin DFN	-40 to +105 °C
5PB1106CMGI		Cut Tape	16-pin QFN	-40 to +105 °C
5PB1106CMGI8		Tape and Reel	16-pin QFN	-40 to +105 °C
5PB1108CMGI		Cut Tape	16-pin QFN	-40 to +105 °C
5PB1108CMGI8		Tape and Reel	16-pin QFN	-40 to +105 °C
5PB1110NDGI		Tubes	20-pin QFN	-40 to +105 °C
5PB1110NDGI8		Tape and Reel	20-pin QFN	-40 to +105 °C

"G" after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

#### **Revision History**

Rev.	Date	Originator	Description of Change
А	03/20/15	B. Chandhoke	Initial release.



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